



Semicon Taiwan: Booth 2522, 1st floor

ERS showcases Thermal Chuck and eWLB Test Product Line-up at Semicon Taiwan

MUNICH, September 1, 2016 – ERS electronic GmbH, the innovation leader in the market of thermal test solutions for semiconductor production, will showcase its product line at the Semicon Taiwan trade fair (September 7 – 9). At the exhibition, ERS shares its stand with its sales partner Chain Logic International Corp. (CLIC), highlighting the trusting and fruitful cooperation between ERS and CLIC.

ERS Asia General Manager Harald Ibele will be attending the event on behalf of ERS and is available to meet for any questions regarding wafer probe or eWLB style warpage adjust equipment and processes. “This joint exhibition presence highlights the trusting and fruitful cooperation between ERS and CLIC”, said Ibele. “With the proven quality of our products and services we will continue our successful relationship.”

ERS excels in high accuracy, low noise thermal chucks for high-end wafer test for technologically demanding segments of the semiconductor industry such as the automotive, medical and aerospace markets as well as R&D.

Semicon Taiwan is the premiere event for the semiconductor industry in Asia, bringing together manufacturers, suppliers and business customers from all over the world. Taiwan is known for having the largest concentration of foundries and test houses globally. With its current line-up of technologically advanced test solutions, ERS, together with its distribution partner Chain Logic, is extremely well positioned to break into this demanding market. ERS’ latest developments in the field of Thermal Wafer Chucks will take center stage at the company’s exhibits in booth 2522, 1st floor.

Semicon Taiwan, one of the largest events of its kind around the globe, is expected to attract 43.000 visitors and 3.300 program participants; more than 700 exhibitors from all over the world will showcase their products in 1600+ booths.

About ERS:

ERS electronic GmbH, based in Germering near Munich, has been producing innovative thermal test solutions for the semiconductor industry for 45 years. The company has gained an outstanding reputation in the sector, notably with its fast and accurate thermal chuck systems for test temperatures ranging from -65°C to +500°C for analytical, parameter-related and manufacturing tests. Today, thermal chuck systems developed by ERS in its product families AC3, AirCool©, AirCool© plus and PowerSense© are an integral component in all larger-sized wafer probers right across the chip industry.

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